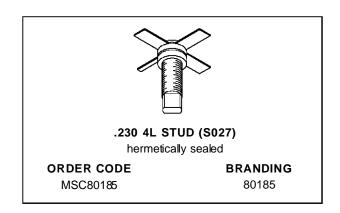
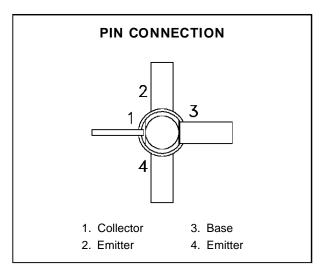


# MSC80185

# RF & MICROWAVE TRANSISTORS GENERAL PURPOSE LINEAR APPLICATIONS

- EMITTER BALLASTED
- CLASS A LINEAR OPERATION
- COMMON EMITTER
- VSWR CAPABILITY 20:1 @ RATED CONDITIONS
- ft 3.2 GHz TYPICAL
- NOISE FIGURE 12.0 dB @ 2 GHz
- $\blacksquare$  P<sub>OUT</sub> = 28 dBm MIN. @ 2.0 GHz





#### DESCRIPTION

The MSC80185 is a hermetically sealed NPN power transistor featuring a unique matrix structure. This device is specifically designed for Class A linear applications to provide high gain and high output power at the 1.0 dB compression point.

## **ABSOLUTE MAXIMUM RATINGS** $(T_{case} = 25^{\circ}C)$

Symbol	Parameter	Value	Unit	
P <sub>DISS</sub>	Power Dissipation (see Safe Area)	_	W	
Ic	Device Bias Current	300	mA	
V <sub>CE</sub>	Collector-Emitter Bias Voltage*	20	V	
TJ	Junction Temperature	200	°C	
T <sub>STG</sub>	Storage Temperature	- 65 to +200	°C	

### THERMAL DATA

R <sub>TH(j-c)</sub>	Junction-Case Thermal Resistance*	35	°C/W

<sup>\*</sup>Applies only to rated RF amplifier operation

October 1992 1/6

# **ELECTRICAL SPECIFICATIONS** (T<sub>case</sub> = 25°C)

# STATIC

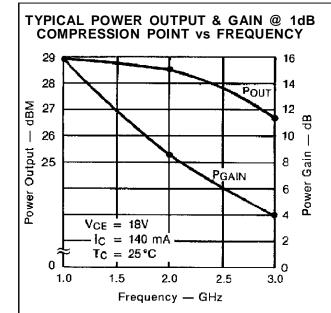
Symbol	Test Conditions	Value			11:4		
		Min.	Тур.	Max.	Unit		
BV <sub>CBO</sub>	I <sub>C</sub> = 1mA	$I_E = 0mA$		50	_		V
BV <sub>EBO</sub>	I <sub>E</sub> = 1mA	$I_C = 0mA$		3.5	_	_	V
BVCEO	IC = 5mA	$I_B = 0mA$		20	_	_	V
ICEO	V <sub>CE</sub> = 18V			_	_	0.5	mA
h <sub>FE</sub>	V <sub>CE</sub> = 5V	I <sub>C</sub> = 100mA		15		120	_

# **DYNAMIC**

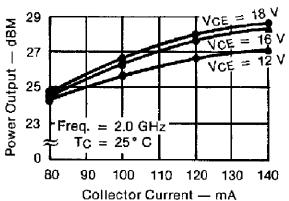
Cumbal	Test Conditions			Value			IImi4
Symbol				Min.	Тур.	Max.	Unit
G <sub>P</sub> *	f = 2.0 GHz	$P_{OUT} = 28 \text{ dBm}$		7.5	8.5	_	dB
$\Delta G_P^*$	f = 2.0 GHz	P <sub>OUT</sub> = 28 dBm	$\Delta P_{OUT} = 10 \text{ dB}$		_	1	dB
СОВ	f = 1 MHz	V <sub>CB</sub> = 28 V		-	_	3.0	pF

\* Note:  $V_{CE} = 18V$  $I_{C} = 140 \text{mA}$ 

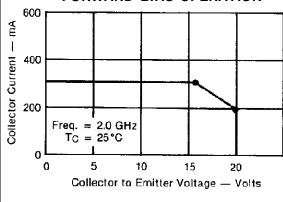
#### TYPICAL PERFORMANCE



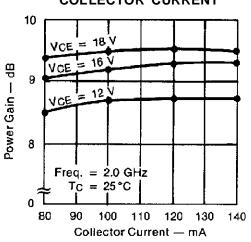




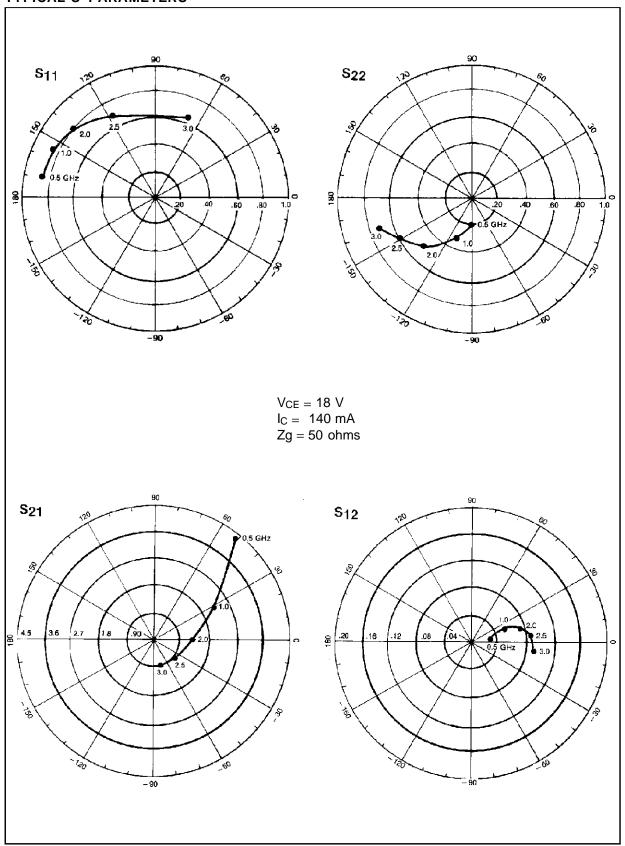




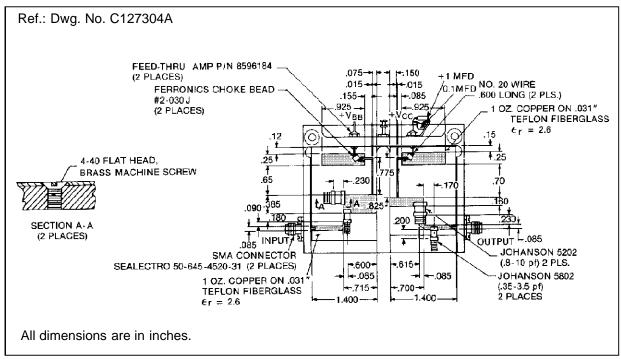
## TYPICAL LINEAR GAIN vs COLLECTOR CURRENT



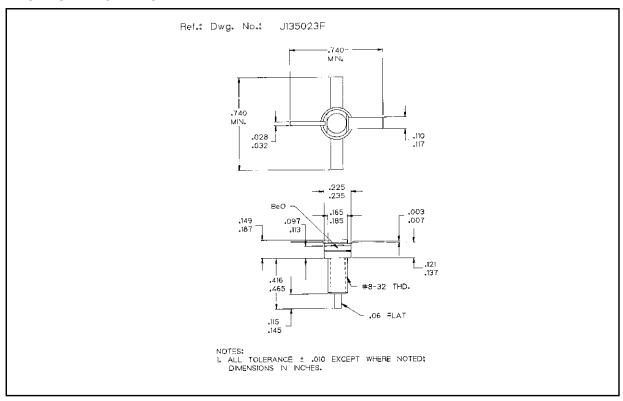
# TYPICAL S-PARAMETERS



## **TEST CIRCUIT**



# PACKAGE MECHANICAL DATA



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